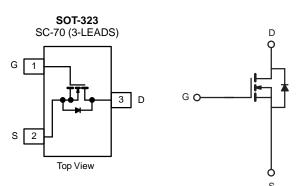


### MCH3476-VB Datasheet

# N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup> Q <sub>g</sub> (Typ.)				
	0.036 at V <sub>GS</sub> = 10 V	4				
20	0.040 at V <sub>GS</sub> = 4.5 V	3.8	4 nC			
	0.048 at V <sub>GS</sub> = 2.5 V	3.6				



#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- Portable Devices
  - Load Switch
  - Battery Switch
- · Load Switch for Motors, Relays and Solenoids

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	20	V	
Gate-Source Voltage	V <sub>GS</sub>	± 12	v	
	T <sub>C</sub> = 25 °C		4 <sup>a</sup>	
Continuous Brain Compant (T., 450.9C)	T <sub>C</sub> = 70 °C	1 . [	3.6 <sup>a</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	4 <sup>a, b, c</sup>	
	T <sub>A</sub> = 70 °C	1	3.7 <sup>b, c</sup>	А
Pulsed Drain Current (t = 300 µs)	I <sub>DM</sub>	20		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		2.3 <sup>a</sup>	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	1.3 <sup>b, c</sup>	
	T <sub>C</sub> = 25 °C		2.8	
Maximum Dayor Dissination	T <sub>C</sub> = 70 °C		1.8	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.56 <sup>b, c</sup>	vv
	T <sub>A</sub> = 70 °C	1 [	1.0 <sup>b, c</sup>	
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	60	80	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	34	45	C/VV		

#### Notes:

- a. Package limited,  $T_C = 25$  °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					•		
Drain-Source Breakdown Voltage V <sub>DS</sub>		$V_{GS} = 0 \text{ V, } I_D = 250  \mu\text{A}$	20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		23	3	m) //00	
$V_{GS(th)}$ Temperature Coefficient $\Delta V_{GS(th)}$		I <sub>D</sub> = 250 μA		- 3.2		mV/°(	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	0.6		1.3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 0.5		
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V			± 25	μΑ	
Zoro Coto Voltogo Droip Current		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	15			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$		0.036			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.6 A		0.040		Ω	
		V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 1.5 A		0.048			
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 3.7 A		17		S	
Dynamic <sup>b</sup>				•	•		
Total Cata Chausa	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.7 \text{ A}$		8.8	13.5	nC	
Total Gate Charge				4	6		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.7 \text{ A}$		0.9			
Gate-Drain Charge	Q <sub>gd</sub>			1.1			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	kΩ	
Turn-On Delay Time	t <sub>d(on)</sub>			0.29	0.58		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 4.1 \Omega$		0.4	0.8		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \approx 3.7 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		1.9	3.8		
Fall Time	t <sub>f</sub>			0.75	1.5		
Turn-On Delay Time	t <sub>d(on)</sub>			0.1	0.2	μs	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 4.1 \Omega$		0.15	0.3		
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \approx 3.7 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		3	6		
Fall Time	t <sub>f</sub>	1		0.75	1.5		
Drain-Source Body Diode Characteristic	s			•	•		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.3		
Pulse Diode Forward Current	I <sub>SM</sub>				20	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 3.7 A, V <sub>GS</sub> = 0 V		0.85	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			12	25	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 2 7 A 41/44 400 A/45 T 25 20		5	10	nC	
Reverse Recovery Fall Time t <sub>a</sub>		$I_F = 3.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		6.5			
Reverse Recovery Rise Time	t <sub>b</sub>			5.5		ns	

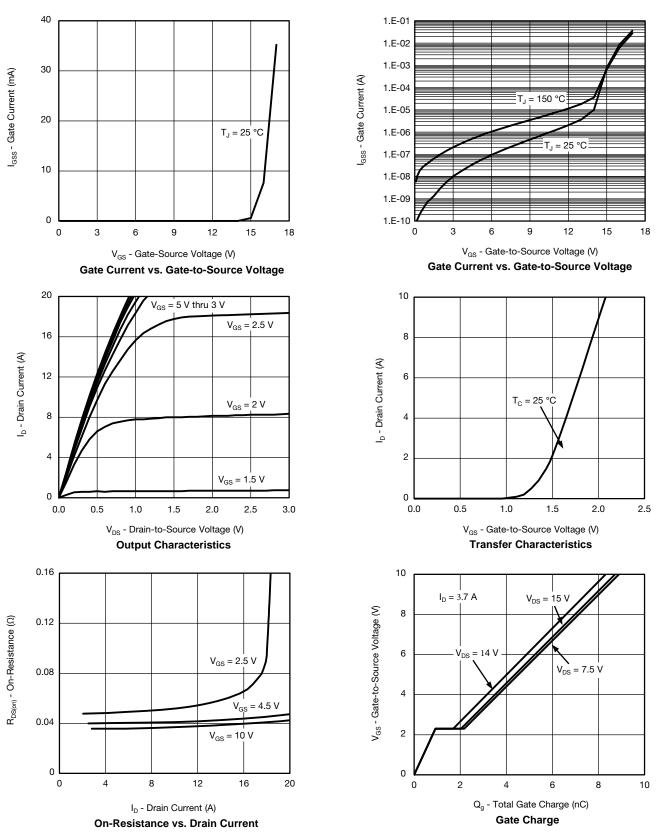
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

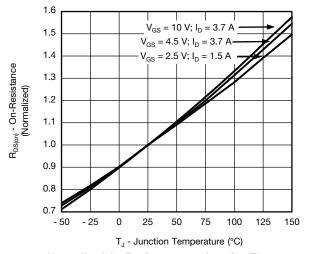


# **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

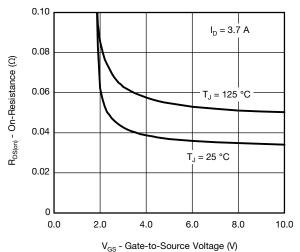




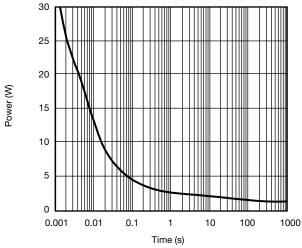
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



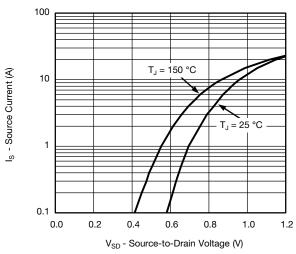
#### Normalized On-Resistance vs. Junction Temperature



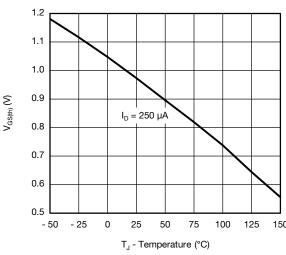
On-Resistance vs. Gate-to-Source Voltage



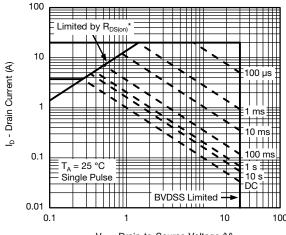
Single Pulse Power, Junction-to-Ambient



Source-Drain Diode Forward Voltage



Threshold Voltage

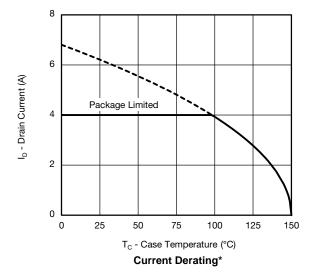


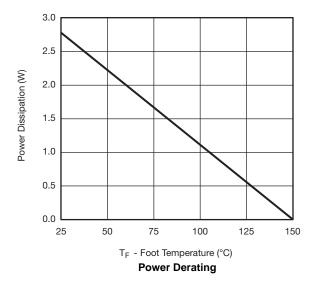
 $\rm V_{DS}$  - Drain-to-Source Voltage (V)  $^*$   $\rm V_{GS}$  > minimum  $\rm V_{GS}$  at which  $\rm R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient



## **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

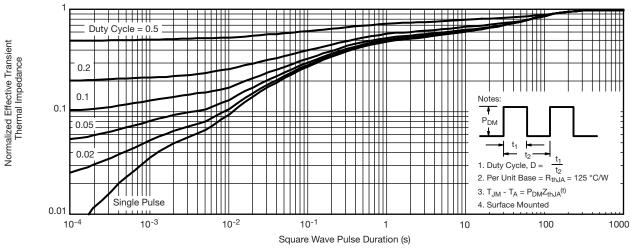




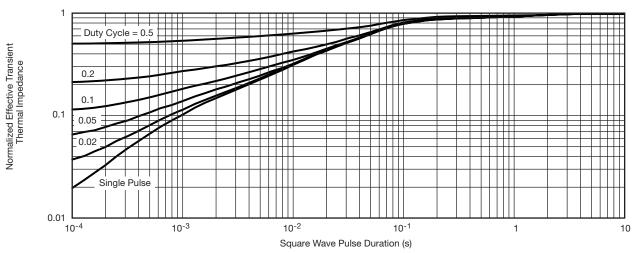
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



### **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



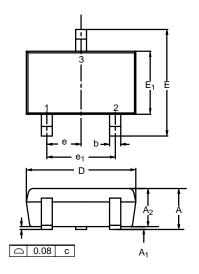
Normalized Thermal Transient Impedance, Junction-to-Ambient

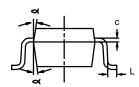


Normalized Thermal Transient Impedance, Junction-to-Foot



### SC-70: 3-LEADS





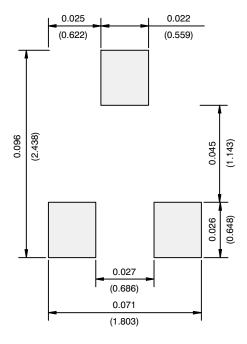
	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	_	0.043
$A_1$	-	-	0.10	-	_	0.004
A <sub>2</sub>	0.80	-	1.00	0.031	_	0.039
b	0.25	-	0.40	0.010	_	0.016
С	0.10	-	0.25	0.004	_	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Ε	1.80	2.10	2.40	0.071	0.083	0.094
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
Þ	7°Nom			7°Nom		
ECN: S-03946—Rev. C, 09-Jul-01						

DWG: 5549

服务热线:400-655-8788 7



#### **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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